



Product/Process Change Notice - PCN 11_0306 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Conversion of AD8137 from Punched to Sawn leadframe and Transfer of Backend Process to STATS ChipPAC Malaysia

Publication Date: 01-Feb-2012

Effectivity Date: 01-May-2012 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Correct assembly location in BOM attachment and add specific POD details for 3x3x0.75mm package.

Description Of Change

ADI has qualified and will be utilizing subcontractor Stats ChipPAC in Malaysia (SCM) for assembly and test of select LFCSP products in a 3x3 package. ADI has also qualified SCM's standard bill of materials in a Sawn singulated leadframe. Pin1 indicator will be laser marked as part of the change. See attachments for BOM changes, pin 1 marking comparison and package outline differences.

Reason For Change

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified SCM-Malaysia as an assembly and test site will ensure continued source of product supply. ADI's backend subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The device function and reliability as specified by the product datasheet will be unaffected by these changes. The Foot Print Dimension will remain the same for both punch and sawn LFCSP package.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_11_0306_Rev_A_LFCSP Qual Report.pdf

Attachment 2: Type: Marking Comparison

ADI_PCN_11_0306_Rev_A_LFCSP Pin 1 Marking.pdf

Attachment 3: Type: Package Outline Drawing

ADI_PCN_11_0306_Rev_A_LFCSP POD.pdf

Attachment 4: Type: Test Correlation Report

ADI_PCN_11_0306_Rev_A_AD8137 Test Product Transfer Qualification.docx

Attachment 5: Type: Other

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan:	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (4)

AD8137 / AD8137YCPZ-R2	AD8137 / AD8137YCPZ-REEL	AD8137 / AD8137YCPZ-REEL7	AD8137 / ADW13012Z	
------------------------	--------------------------	---------------------------	--------------------	--

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	11-Jan-2012	Initial Release
Rev. A	01-Feb-2012	Correct assembly location in BOM attachment and add specific POD details for 3x3x0.75mm package.

Analog Devices, Inc.

DocId:1836 Parent DocId:None Layout Rev.6